### 1.6x0.8mm SMD CHIP LED LAMP

Part Number: APHM1608SGCT

Super Bright Green

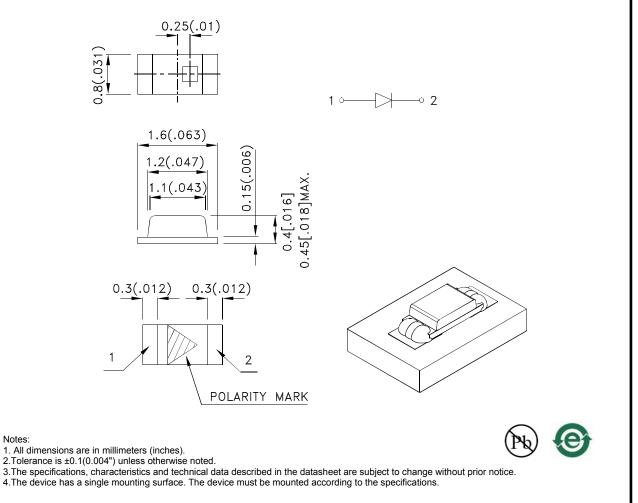
#### **Features**

- 1.6mmx0.8mm SMT LED, 0.45mm max. thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

#### Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

### **Package Dimensions**



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Selection Guide									
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]				
			Min.	Тур.	201/2				
APHM1608SGCT	Super Bright Green (GaP)	WATER CLEAR	10	25	120°				

Notes:

01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	I⊧=20mA
IR	Reverse Current	Super Bright Green		10	uA	VR=5V

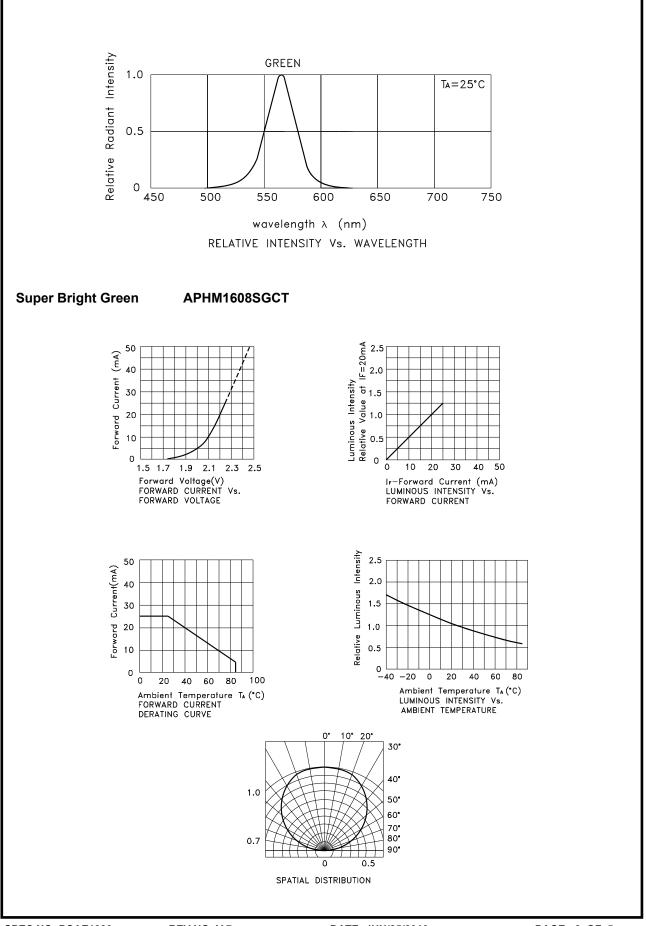
Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units
Power dissipation	62.5	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Electrostatic Discharge Threshold (HBM)	8000	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

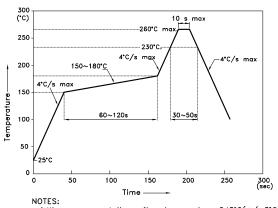
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



### APHM1608SGCT

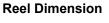
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

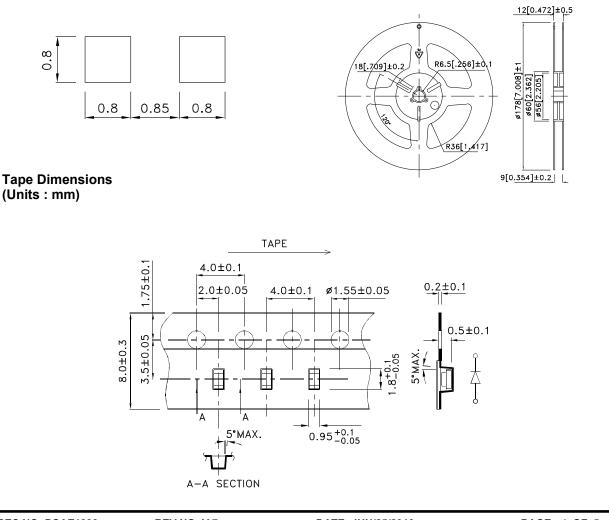
Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

**Recommended Soldering Pattern** (Units : mm; Tolerance: ± 0.1)





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